## Specifications

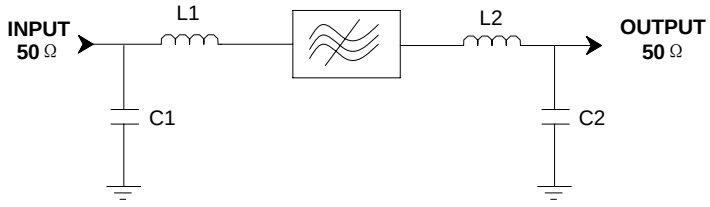
| Parameter | Unit | Minimum | Typical | Maximum |
|---|---|---|---|---|
| *Center Frequency* | MHz | 159.92 | 160 | 160.08 |
| *Insertion Loss* | dB | - | 29.5 | 31 |
| *3 dB Bandwidth* | MHz | 12.7 | 12.74 | - |
| *30 dB Bandwidth* | MHz | - | 13.41 | 13.5 |
| *40 dB Bandwidth* | MHz | - | 13.52 | 13.9 |
| *50 dB Bandwidth* | MHz | - | 13.66 | - |
| *Passband Variation* | dB | - | 1 | 1.2 |
| *Absolute Delay* | usec | - | 3.6 | 4 |
| *Ultimate Rejection* | dB | 50 | 54 | - |
| *Material Temperature coefficient* | KHz/°C | -2.88 | | |
| *Ambient Temperature* | °C | 25 | | |
| *Package Size* | DIP2712 (27.0x12.8x4.7mm3) | | | |



**Notes:**

1. All specifications are based on the test circuit shown
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. This is the optimum impedance in order to achieve the performance show

## Matching Configuration




**L1=L2=27nH**

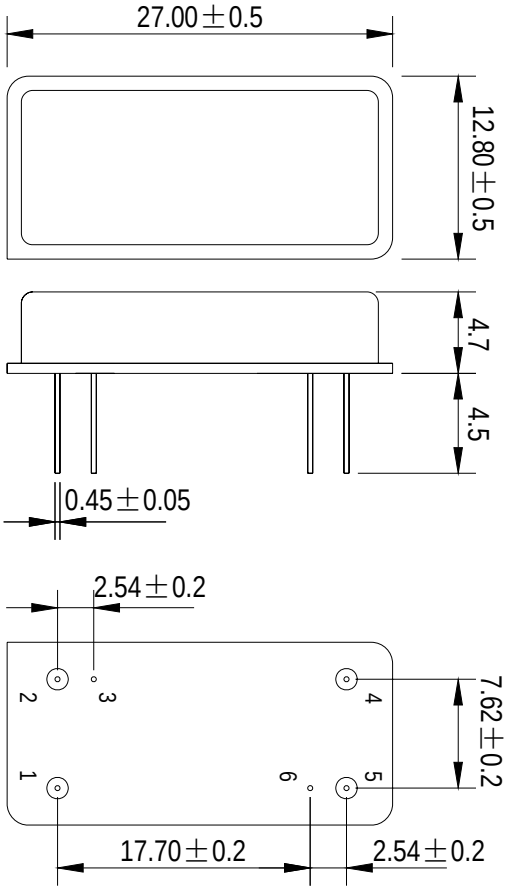
**C1=47pF C2=39pF**

**Source/Load Impedance=50 ohm**

Notes - Component values may change depending on board layout.

## Package Dimension





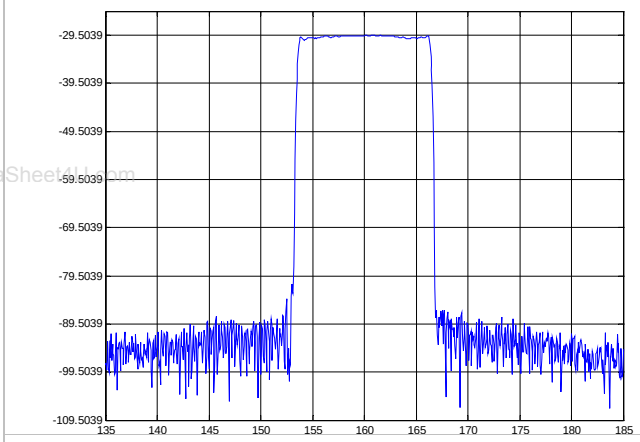

| | |
|---|---|
| Input | 1 |
| Output | 5 |
| Ground | 2,3,4,6 |

**Package: DIP2712**

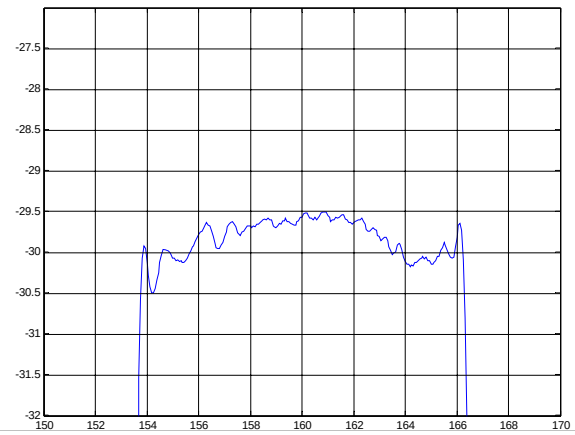
**Unit: mm**

## *Typical Performance*

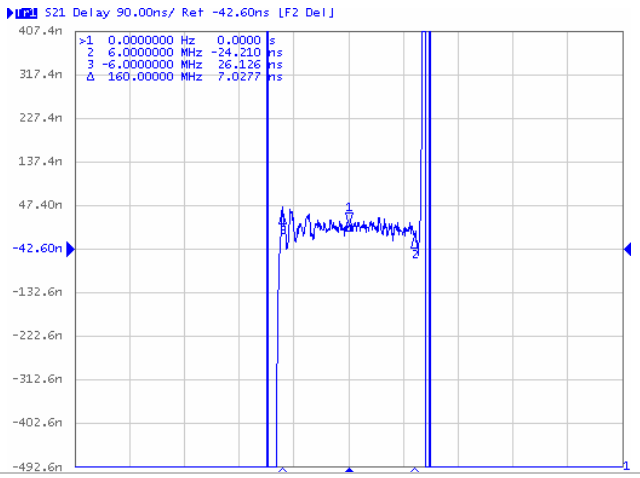
### Frequency Respond



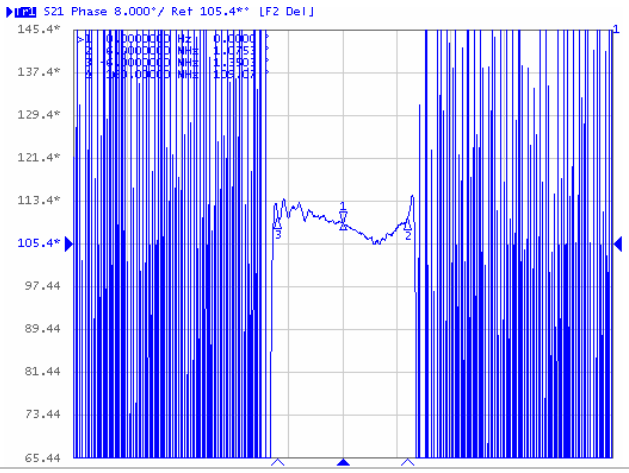

### Passband Respond



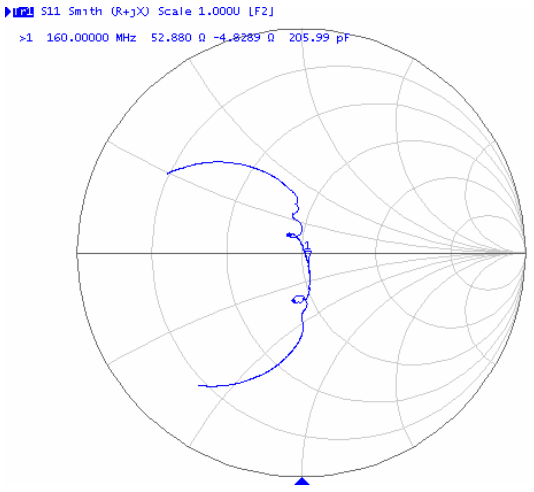

### Group Delay Variation(f0±6MHz)




### Phase Linearity(f0±6MHz)




### Smith Chart S11




### Smith Chart S22